

2SC2258(A)

Rev.E Mar.-2016

描述 / Descriptions

TO-126F 塑封封装 NPN 半导体三极管。Silicon NPN transistor in a TO-126F Plastic Package.

特征 / Features

耐压高, f_T 高。

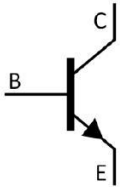
High V_{CEO} , high f_T .

用途 / Applications

用于普通高压放大, 彩电色度输出。

High voltage general amplifier, TV video output amplifier.

内部等效电路 / Equivalent Circuit



引脚排列 / Pinning



PIN1 : Emitter

PIN 2 : Collector

PIN 3 : Base

放大及印章代码 / h_{FE} Classifications & Marking

见印章说明。See Marking Instructions.

极限参数 / Absolute Maximum Ratings(Ta=25°C)

参数 Parameter	符号 Symbol	数值 Rating	单位 Unit	
Collector to Base Voltage	V _{CBO}	2SC2258	250	V
		2SC2258A	300	
Collector to Emitter Voltage	V _{CEO}	2SC2258	250	V
		2SC2258A	300	
Emitter to Base Voltage	V _{EBO}	7.0	V	
Collector Current – Continuous(Pulse)	I _{CP}	150	mA	
Collector Current - Continuous	I _C	100	mA	
Collector Power Dissipation	P _C	1.0	W	
Collector Power Dissipation*	*P _C (T _C =25°C)	4.0*	W	
Junction Temperature	T _j	150	°C	
Storage Temperature Range	T _{stg}	-55~150	°C	

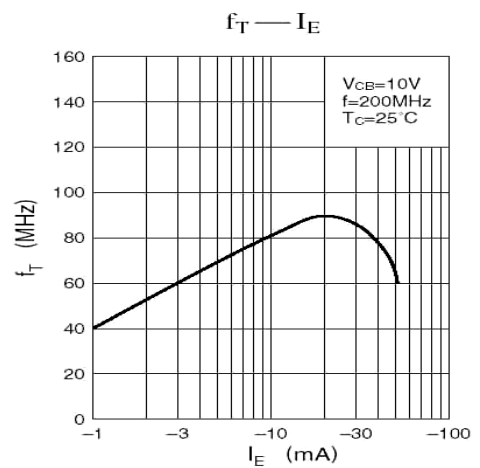
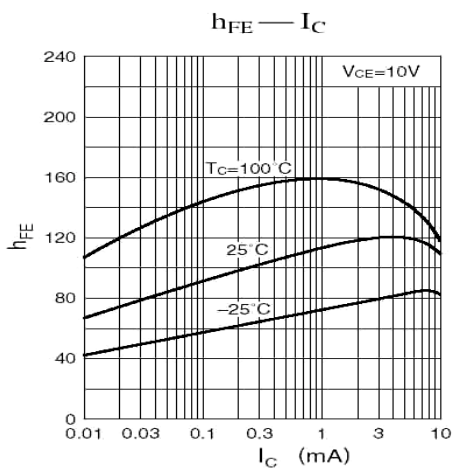
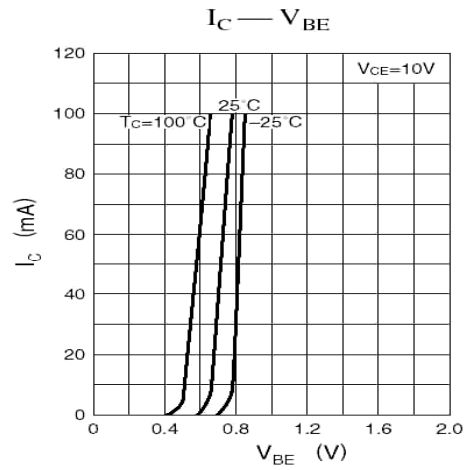
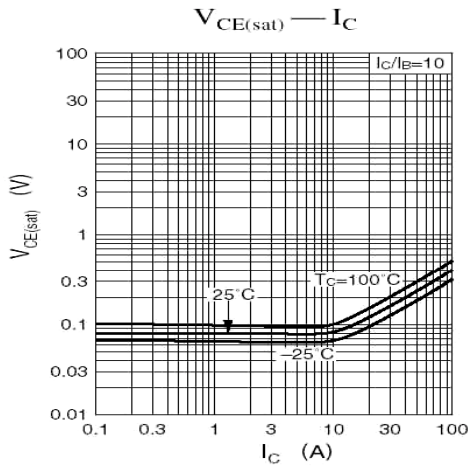
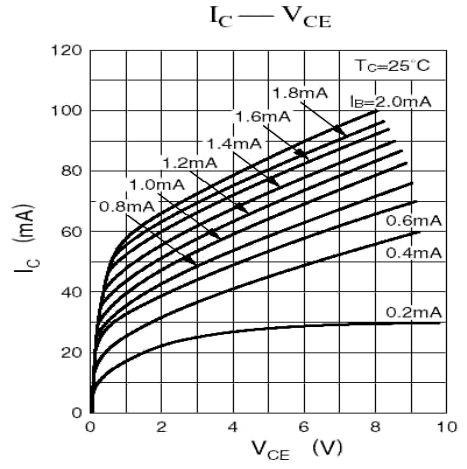
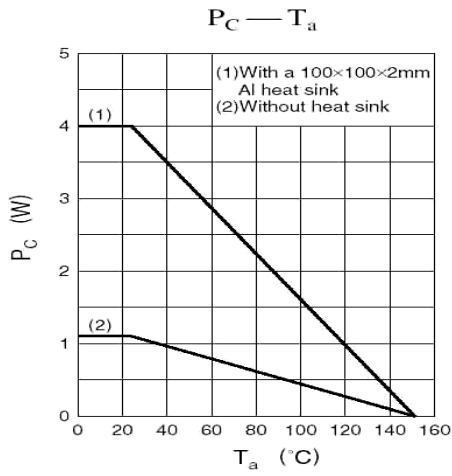
* 带铝散热片尺寸：100×100×20mm。

* With a 100×100×20mm Al heat sink.

电性能参数 / Electrical Characteristics(Ta=25°C)

参数 Parameter	符号 Symbol	测试条件 Test Conditions	最小值 Min	典型值 Typ	最大值 Max	单位 Unit
Emitter to Base Breakdown Voltage	V _{EBO}	I _E =0.1mA I _C =0	7.0			V
Collector Cut-Off Current	I _{CEO}	V _{CE} =250V I _B =0			100	μA
DC Current Gain	h _{FE(1)}	V _{CE} =20V I _C =40mA	40		200	
	h _{FE(2)}	V _{CE} =50V I _C =5.0mA	30			
Collector to Emitter Saturation Voltage	V _{CE(sat)}	I _C =50mA I _B =5.0mA			1.2	V
Base to Emitter Voltage	V _{BE}	V _{CE} =20V I _C =40mA			1.2	V
Transition Frequency	f _T	V _{CB} =10V I _C =10mA		100		MHz
Reverse Transfer Capacitance	C _{ob}	V _{CB} =50V I _E =0 f=1.0MHz		3.0	4.5	pF

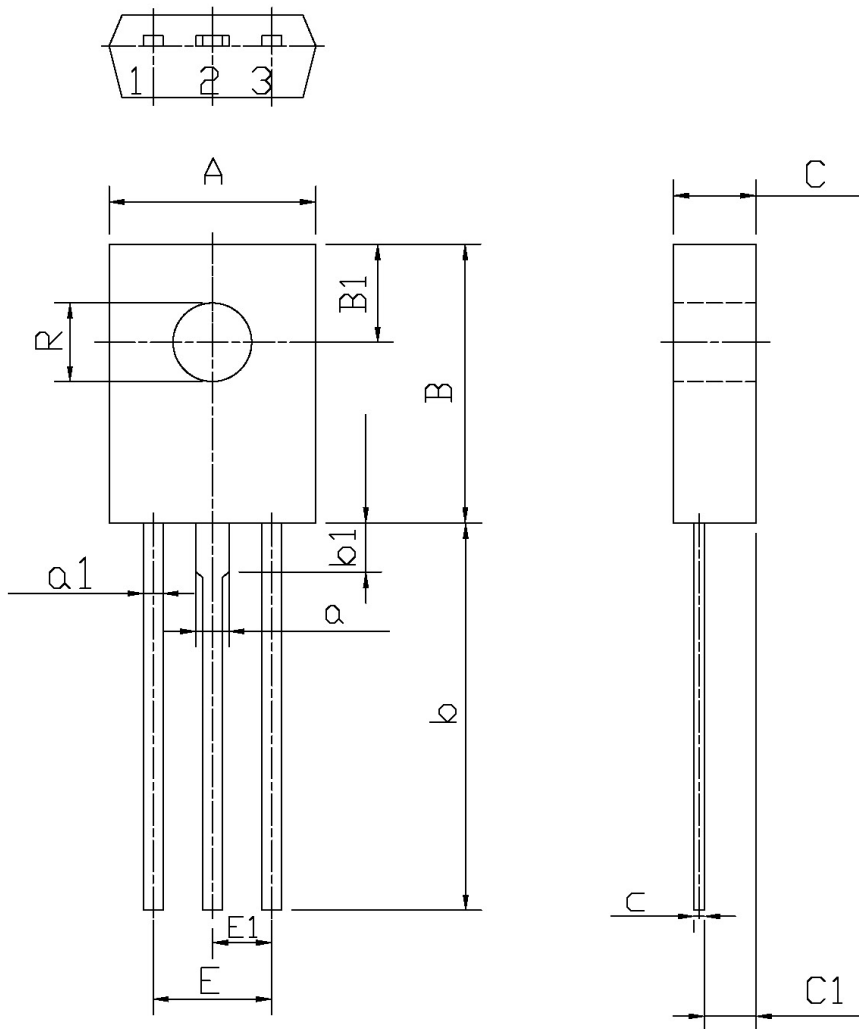
电参数曲线图 / Electrical Characteristic Curve



外形尺寸图 / Package Dimensions

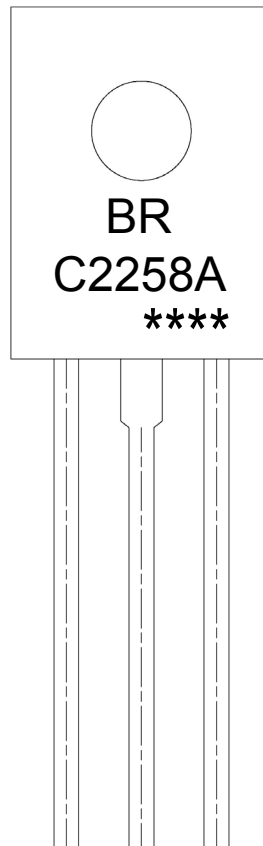
T0-126F

单位: mm



Symbol	Dimensions In Millimeters		Symbol	Dimensions In Millimeters	
	Min	Max		Min	Max
A	7.8	8.2	a1	0.66	0.86
B	10.8	11.2	E	4.4	4.8
B1	3.8	4.2	C	3.1	3.3
R	2.95	3.15	C1	1.9	2.1
b	14	16	c	0.3	0.6
b1	1.9		a	1.27	
E1	2.1	2.5			

印章说明 / Marking Instructions



说明：

BR： 为公司代码

C2258A： 为型号代码

****： 为生产批号代码，随生产批号变化。

Note:

BR: Company Code

C2258A: Product Type.

****: Lot No. Code, code change with Lot No.

波峰焊温度曲线图(无铅) / Temperature Profile for Dip Soldering(Pb-Free)



说明：

- 1、预热温度 25 ~ 150°C，时间 60 ~ 90sec;
- 2、峰值温度 255±5°C，时间持续为 5±0.5sec;
- 3、焊接制程冷却速度为 2 ~ 10°C/sec.

Note:

- 1.Preheating:25~150°C, Time:60~90sec.
- 2.Peak Temp.:255±5°C, Duration:5±0.5sec.
3. Cooling Speed: 2~10°C/sec.

耐焊接热试验条件 / Resistance to Soldering Heat Test Conditions

温度：270±5°C

时间：10±1 sec.

Temp.:270±5°C

Time:10±1 sec

包装规格 / Packaging SPEC.

散件包装 / BULK

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm ³)		
	Units/Tube 只/套管	Tubes/Inner Box 套管/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Tube 套管	Inner Box 盒	Outer Box 箱
TO-126/F	500	6	3,000	5	15,000	135×190	237×172×102	560×245×195

套管包装 / TUBE

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm ³)		
	Units/Tube 只/套管	Tubes/Inner Box 套管/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Tube 套管	Inner Box 盒	Outer Box 箱
TO-126/F	65	26	1,690	5	8,450	532×31×5.6	555×164×50	575×290×180

使用说明 / Notices